

## C0805C334J5REC

ESD SMD Comm X7R, Ceramic, 0.33 uF, 5%, 50 VDC, X7R, SMD, MLCC, Temperature Stable, Electro Static Discharge, Class II, 0805, 0.7 mm



Click [here](#) for the 3D model.

### General Information

Series	ESD SMD Comm X7R
Style	SMD Chip
Description	SMD, MLCC, Temperature Stable, Electro Static Discharge, Class II
Features	Temperature Stable, Class II
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Typical Component Weight	13 mg
Shelf Life	78 Weeks
MSL	1

### Dimensions

Chip Size	0805
L	2mm +/-0.2mm
W	1.25mm +/-0.2mm
T	0.9mm +/-0.10mm
S	0.7mm MIN
B	0.5mm +/-0.25mm

### Packaging Specifications

Packaging	Bulk, Bag
Packaging Quantity	1

### Specifications

Capacitance	0.33 uF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	5%
Voltage DC	50 VDC
ESD Level per AEC-Q200	25,000 V ESD Level
Dielectric Withstanding Voltage	125 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	X7R
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	15%, 1kHz 1.0Vrms
Dissipation Factor	2.5% 1 kHz 1.0Vrms
Aging Rate	3% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	1.5152 GOhms

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